

Qualcomm Technologies Announces Next-Generation Qualcomm® RF360™ Front-End Solutions for Sleeker and More Efficient Mobile Devices

-- Includes World's First Announced 40 MHz Envelope Tracker, Designed to Extend Battery Life for 4G+ Smartphones, and Comprehensive, Multi-tier Antenna Tuner and Power Amplifier Solutions --

SAN DIEGO, Feb. 17, 2016 /PRNewswire/ -- Qualcomm Incorporated (NASDAQ: QCOM) today announced that its subsidiary, Qualcomm Technologies, Inc., is introducing a suite of next-generation Qualcomm® RF360™ technologies that enhance its front-end solutions in premium and entry-level design tiers. These include the world's first announced 40 MHz envelope tracker (QET4100), a comprehensive multi-tier portfolio of antenna tuners and antenna switches (QAT2514, QAT2522) and a RF front-end power amplifier (PA) solution (QPA4373, QPA4351) purpose-built for the entry-level tier. These technologies span across all tiers of mobile devices and will provide original equipment manufacturers (OEMs) the ability to build sleeker phones with a better user experience, which includes superior battery life, call reliability and quality, data speeds, network coverage and roaming capabilities.

World's first announced 40 MHz Envelope Tracking solution

Qualcomm Technologies introduced a major advancement in LTE power efficiency with the Qualcomm RF360 QET4100, the world's first announced 40 MHz Envelope Tracking solution for LTE FDD and LTE TDD. The QET4100 works intelligently with the Qualcomm® Snapdragon™ X16 LTE modem and QPA4340, Qualcomm Technologies' new high band power amplifier and switch module, to deliver power-efficient connectivity for the next generation of ultra-fast 4G+ mobile devices supporting up-link carrier aggregation. The QPA4340 high-band PA and switch solution is a small footprint module designed to deliver superior power output performance in front-end architectures for carrier aggregation.

Comprehensive multi-tier antenna tuning and antenna switch portfolio

With the introduction of QAT2514, a cost-optimized SP4T Aperture Tuner, Qualcomm Technologies extended its leading antenna tuning capability to its Snapdragon 600 and 400 processor tiers. Qualcomm Technologies has designed the QAT2514 with layer transfer technology for superior linearity and isolation performance. This technology is also integrated into the new QAT2522 DPDT antenna switch, allowing OEMs to implement Qualcomm® TruSignal™ Multi-Antenna Boost (antenna switch diversity) in the Snapdragon 800, 600 and 400 tiers.

With these new products OEM customers can now choose from advanced closed-loop tuning (TruSignal Antenna Boost), open-loop tuning, aperture tuning, antenna switch diversity (TruSignal Multi-Antenna Boost) or a hybrid solution, giving them the flexibility to implement the antenna processing technology optimal for their target cost-performance mix. Qualcomm Technologies also provides a broad suite of software and hardware support tools that help customers implement these advanced antenna tuning technologies with easier design-in effort and faster time to launch.

Next-generation power amplifier solution for entry-level Snapdragon All Mode designs

To allow cost-effective Snapdragon All Mode front-end designs for China and emerging regions, Qualcomm Technologies also introduced a purpose-built entry-level Qualcomm RF360 solution comprising of QPA4373 and QPA4351 power amplifiers. The QPA4373 and QPA4351 PAs are designed with cost and flexibility in mind, allowing OEMs to easily customize front-end configurations for different regions using one PCB design with pop/de-pop options. The QPA4373/QPA4351 solution currently supports Snapdragon 652, 650, 625, 617, 430, 425, 210, 212 processors and Snapdragon X5 LTE modem (9x07).

These new Qualcomm RF360 solutions are designed to help premium-tier customers improve device performance with reduced time to launch, and lower development effort and costs. Customers targeting lower-tier designs will benefit from high flexibility, cost-effective and improved performance through advanced technologies now being made available in lower design tiers.

"We are committed to pushing the envelope on advanced RF front-end technologies while also rounding out our RFFE portfolio to bring next-generation, cost-effective solutions to our customers in all tiers," said James Wilson II, vice president

and general manager of RFFE, Qualcomm Technologies, Inc. "We have done this through system level and component level innovation and R&D investment, as well as key strategic acquisitions."

The antenna tuner solutions are in production and will be available in the first half of 2016. Samples for QET4100 envelope tracker and QPA4373 are available on request. Samples of QPA4351 and QPA4340 ET PA will be available in April 2016.

About Qualcomm Incorporated

Qualcomm Incorporated (NASDAQ: QCOM) is a world leader in 3G, 4G and next-generation wireless technologies. Qualcomm Incorporated includes Qualcomm's licensing business, QTL, and the vast majority of its patent portfolio. Qualcomm Technologies, Inc., a subsidiary of Qualcomm Incorporated, operates, along with its subsidiaries, substantially all of Qualcomm's engineering, research and development functions, and substantially all of its products and services businesses, including its semiconductor business, QCT. For more than 30 years, Qualcomm ideas and inventions have driven the evolution of digital communications, linking people everywhere more closely to information, entertainment and each other. For more information, visit Qualcomm's [website](#), [OnQ blog](#), [Twitter](#) and [Facebook](#) pages.

Qualcomm and Snapdragon are trademarks of Qualcomm Incorporated registered in the United States and other countries. RF360 and TruSignal are trademarks of Qualcomm Incorporated. Qualcomm RF360, Qualcomm Snapdragon and Qualcomm TruSignal are products of Qualcomm Technologies, Inc.

Qualcomm Contacts:

Pete Lancia, Corporate Communications

Phone: 1-858-845-5959

Email: corpcomm@qualcomm.com

Warren Kneeshaw, Investor Relations

Phone: 1-858-658-4813

Email: ir@qualcomm.com

To view the original version on PR Newswire, visit <http://www.prnewswire.com/news-releases/qualcomm-technologies-announces-next-generation-qualcomm-rf360-front-end-solutions-for-sleeker-and-more-efficient-mobile-devices-300221251.html>

SOURCE Qualcomm Incorporated